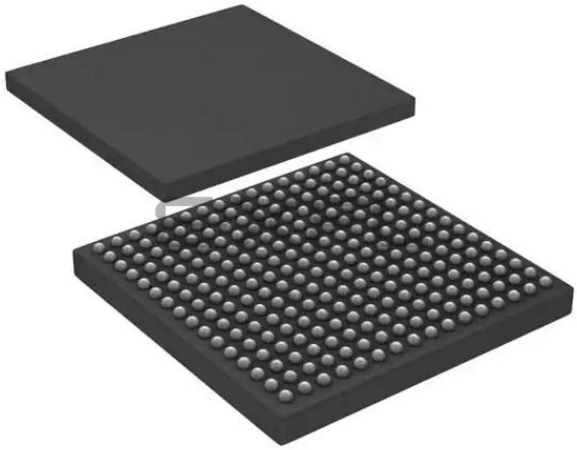

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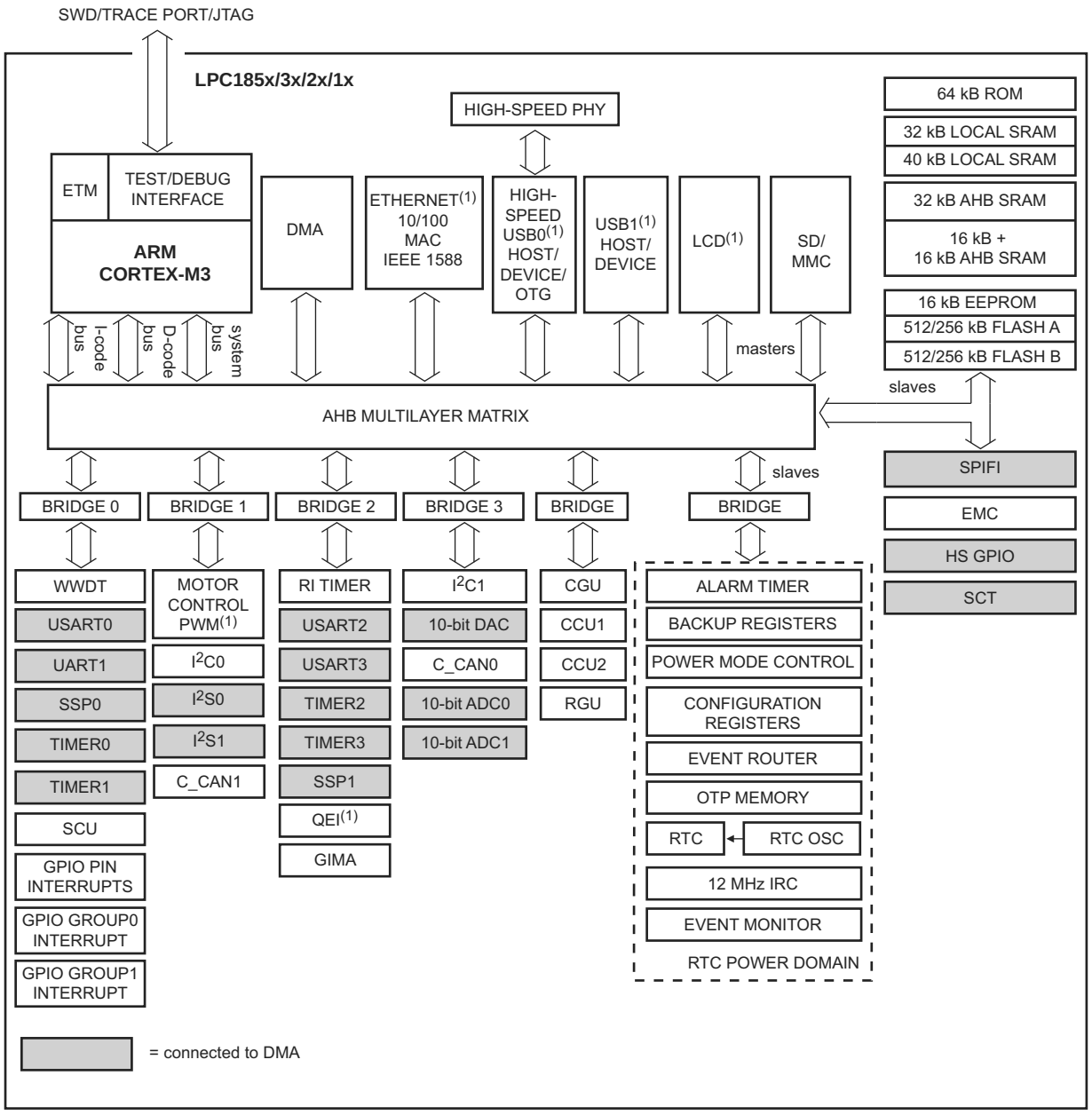
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M3
Core Size	32-Bit Single-Core
Speed	180MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I²C, IrDA, Microwire, QEI, SD, SPI, SSI, SSP, UART/USART, USB, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, I²S, Motor Control PWM, POR, PWM, WDT
Number of I/O	164
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	16K x 8
RAM Size	136K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 16x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	256-LBGA
Supplier Device Package	256-LBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/lpc1833jet256-551

5. Block diagram



(1) Not available on all parts. See Table 2.

Fig 1. LPC185x/3x/2x/1x block diagram

6. Pinning information

6.1 Pinning

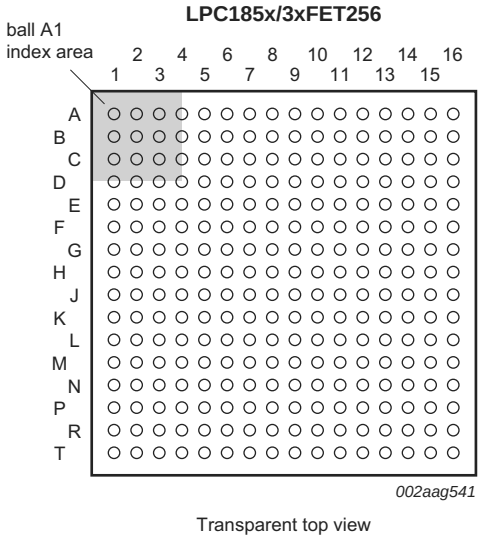


Fig 2. Pin configuration LBGA256 package

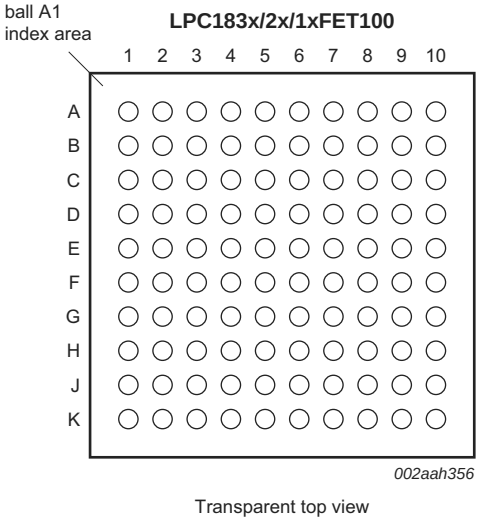


Fig 3. Pin configuration TFBGA100 package

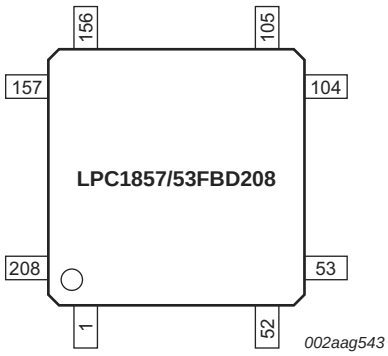


Fig 4. Pin configuration LQFP208 package

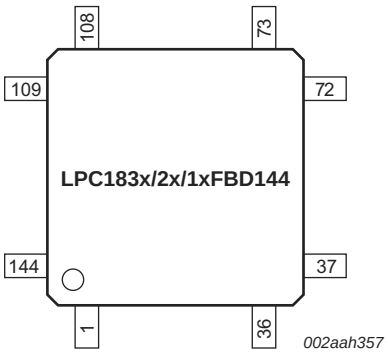


Fig 5. Pin configuration LQFP144 package

6.2 Pin description

On the LPC185x/3x/2x/1x, digital pins are grouped into 16 ports, named P0 to P9 and PA to PF, with up to 20 pins used per port. Each digital pin can support up to eight different digital functions, including General-Purpose I/O (GPIO), selectable through the SCU registers.

The pin name is not indicative of the GPIO port assigned to it.

The parts contain two 10-bit ADCs (ADC0 and ADC1). The input channels of ADC0 and ADC1 on dedicated pins and multiplexed pins are combined in such a way that all channel 0 inputs (named ADC0_0 and ADC1_0) are tied together and connected to both, channel

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P3_8	C10	E7	124	179	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							I/O	**SSP0_MOSI —** Master Out Slave in for SSP0.
							I/O	**SPIFI_CS —** SPIFI serial flash chip select.
							I/O	**GPIO5[11] —** General purpose digital input/output pin.
							I/O	**SSP0_SSEL —** Slave Select for SSP0.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P4_0	D5	-	1	1	[2]	N; PU	I/O	**GPIO2[0] —** General purpose digital input/output pin.
							O	**MCOA0 —** Motor control PWM channel 0, output A.
							I	**NMI —** External interrupt input to NMI.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD13 —** LCD data.
							I/O	**U3_UCLK —** Serial clock input/output for USART3 in synchronous mode.
							-	**R —** Function reserved.
P4_1	A1	-	3	3	[5]	N; PU	I/O	**GPIO2[1] —** General purpose digital input/output pin.
							O	**CTOUT_1 —** SCTimer/PWM output 1. Match output 3 of timer 3.
							O	**LCD_VD0 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD19 —** LCD data.
							O	**U3_TXD —** Transmitter output for USART3.
							I	**ENET_COL —** Ethernet Collision detect (MII interface).
							AI	**ADC0_1 —** ADC0 and ADC1, input channel 1. Configure the pin as GPIO input and use the ADC function select register in the SCU to select the ADC.
P4_2	D3	-	8	12	[2]	N; PU	I/O	**GPIO2[2] —** General purpose digital input/output pin.
							O	**CTOUT_0 —** SCTimer/PWM output 0. Match output 0 of timer 0.
							O	**LCD_VD3 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**LCD_VD12 —** LCD data.
							I	**U3_RXD —** Receiver input for USART3.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P6_11	H12	C9	101	143	[2]	N; PU	I/O	**GPIO3[7] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**EMC_CKEOUT0 —** SDRAM clock enable 0.
							-	**R —** Function reserved.
							O	**T2_MAT3 —** Match output 3 of timer 2.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P6_12	G15	-	103	145	[2]	N; PU	I/O	**GPIO2[8] —** General purpose digital input/output pin.
							O	**CTOUT_7 —** SCTimer/PWM output 7. Match output 3 of timer 1.
							-	**R —** Function reserved.
							O	**EMC_DQMOUT0 —** Data mask 0 used with SDRAM and static devices.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P7_0	B16	-	110	158	[2]	N; PU	I/O	**GPIO3[8] —** General purpose digital input/output pin.
							O	**CTOUT_14 —** SCTimer/PWM output 14. Match output 2 of timer 3.
							-	**R —** Function reserved.
							O	**LCD_LE —** Line end signal.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
P7_1	C14	-	113	162	[2]	N; PU	I/O	**GPIO3[9] —** General purpose digital input/output pin.
							O	**CTOUT_15 —** SCTimer/PWM output 15. Match output 3 of timer 3.
							I/O	**I2S0_TX_WS —** Transmit Word Select. It is driven by the master and received by the slave. Corresponds to the signal WS in the *I^2S-bus specification*.
							O	**LCD_VD19 —** LCD data.
							O	**LCD_VD7 —** LCD data.
							-	**R —** Function reserved.
							O	**U2_TXD —** Transmitter output for USART2.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
P8_4	J2	-	-	39	[2]	N; PU	I/O	**GPIO4[4] —** General purpose digital input/output pin.
							I/O	**USB1_ULPI_D1 —** ULPI link bidirectional data line 1.
							-	**R —** Function reserved.
							O	**LCD_VD7 —** LCD data.
							O	**LCD_VD16 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP0 —** Capture input 0 of timer 0.
P8_5	J1	-	-	40	[2]	N; PU	I/O	**GPIO4[5] —** General purpose digital input/output pin.
							I/O	**USB1_ULPI_D0 —** ULPI link bidirectional data line 0.
							-	**R —** Function reserved.
							O	**LCD_VD6 —** LCD data.
							O	**LCD_VD8 —** LCD data.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP1 —** Capture input 1 of timer 0.
P8_6	K3	-	-	43	[2]	N; PU	I/O	**GPIO4[6] —** General purpose digital input/output pin.
							I	**USB1_ULPI_NXT —** ULPI link NXT signal. Data flow control signal from the PHY.
							-	**R —** Function reserved.
							O	**LCD_VD5 —** LCD data.
							O	**LCD_LP —** Line synchronization pulse (STN). Horizontal synchronization pulse (TFT).
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP2 —** Capture input 2 of timer 0.
P8_7	K1	-	-	45	[2]	N; PU	I/O	**GPIO4[7] —** General purpose digital input/output pin.
							O	**USB1_ULPI_STP —** ULPI link STP signal. Asserted to end or interrupt transfers to the PHY.
							-	**R —** Function reserved.
							O	**LCD_VD4 —** LCD data.
							O	**LCD_PWR —** LCD panel power enable.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							I	**T0_CAP3 —** Capture input 3 of timer 0.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
PA_4	G13	-	-	151	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_9 —** SCTimer/PWM output 9. Match output 3 of timer 3.
							-	**R —** Function reserved.
							I/O	**EMC_A23 —** External memory address line 23.
							I/O	**GPIO5[19] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_0	B15	-	-	164	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_10 —** SCTimer/PWM output 10. Match output 3 of timer 3.
							O	**LCD_VD23 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[20] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_1	A14	-	-	175	[2]	N; PU	-	**R —** Function reserved.
							I	**USB1_ULPI_DIR —** ULPI link DIR signal. Controls the ULP data line direction.
							O	**LCD_VD22 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[21] —** General purpose digital input/output pin.
							O	**CTOUT_6 —** SCTimer/PWM output 6. Match output 2 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PB_2	B12	-	-	177	[2]	N; PU	-	**R —** Function reserved.
							I/O	**USB1_ULPI_D7 —** ULPI link bidirectional data line 7.
							O	**LCD_VD21 —** LCD data.
							-	**R —** Function reserved.
							I/O	**GPIO5[22] —** General purpose digital input/output pin.
							O	**CTOUT_7 —** SCTimer/PWM output 7. Match output 3 of timer 1.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
PD_0	N2	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_15 —** SCTimer/PWM output 15. Match output 3 of timer 3.
							O	**EMC_DQMOUT2 —** Data mask 2 used with SDRAM and static devices.
							-	**R —** Function reserved.
							I/O	**GPIO6[14] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PD_1	P1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							-	**R —** Function reserved.
							O	**EMC_CKEOUT2 —** SDRAM clock enable 2.
							-	**R —** Function reserved.
							I/O	**GPIO6[15] —** General purpose digital input/output pin.
							O	**SD_POW —** SD/MMC power monitor output.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PD_2	R1	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_7 —** SCTimer/PWM output 7. Match output 3 of timer 1.
							I/O	**EMC_D16 —** External memory data line 16.
							-	**R —** Function reserved.
							I/O	**GPIO6[16] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
PD_3	P4	-	-	-	[2]	N; PU	-	**R —** Function reserved.
							O	**CTOUT_6 —** SCTimer/PWM output 7. Match output 2 of timer 1.
							I/O	**EMC_D17 —** External memory data line 17.
							-	**R —** Function reserved.
							I/O	**GPIO6[17] —** General purpose digital input/output pin.
							-	**R —** Function reserved.
							-	**R —** Function reserved.
							-	**R —** Function reserved.

Table 3. Pin description *…continued*

Pin name	LBGA256	TFBGA100	LQFP144	LQFP208		Reset state [1]	Type	Description
Debug pins								
DBGEN	L4	A6	28	41	[2]	I	I	JTAG interface control signal. Also used for boundary scan. To use the part in functional mode, connect this pin in one of the following ways: • Leave DBGEN open. The DBGEN pin is pulled up internally by a 50 kΩ resistor. • Tie DBGEN to VDDIO. • Pull DBGEN up to VDDIO with an external pull-up resistor.
TCK/SWDCLK	J5	H2	27	38	[2]	I; F	I	Test Clock for JTAG interface (default) or Serial Wire (SW) clock.
$\overline{\text{TRST}}$	M4	B4	29	42	[2]	I; PU	I	Test Reset for JTAG interface.
TMS/SWDIO	K6	C4	30	44	[2]	I; PU	I	Test Mode Select for JTAG interface (default) or SW debug data input/output.
TDO/SWO	K5	H3	31	46	[2]	O	O	Test Data Out for JTAG interface (default) or SW trace output.
TDI	J4	G3	26	35	[2]	I; PU	I	Test Data In for JTAG interface.
USB0 pins								
USB0_DP	F2	E1	18	26	[6]	-	I/O	USB0 bidirectional D+ line. Do not add an external series resistor.
USB0_DM	G2	E2	20	28	[6]	-	I/O	USB0 bidirectional D− line. Do not add an external series resistor.
USB0_VBUS	F1	E3	21	29	[6] [7]	-	I	VBUS pin (power on USB cable). This pin includes an internal pull-down resistor of 70 kΩ (typical) ± 30 kΩ.
USB0_ID	H2	F1	22	30	[8]	-	I	Indicates to the transceiver whether connected as an A-device (USB0_ID LOW) or B-device (USB0_ID HIGH). For use with OTG, this pin has an internal pull-up resistor.
USB0_RREF	H1	F3	24	32	[8]	-		12.0 kΩ (accuracy 1 %) on-board resistor to ground for current reference.
USB1 pins								
USB1_DP	F12	E9	89	129	[9]	-	I/O	USB1 bidirectional D+ line. Add an external series resistor of 33 Ω +/- 2 %.
USB1_DM	G12	E10	90	130	[9]	-	I/O	USB1 bidirectional D− line. Add an external series resistor of 33 Ω +/- 2 %.
I^2C-bus pins								
I2C0_SCL	L15	D6	92	132	[10]	I; F	I/O	I^2C clock input/output. Open-drain output (for I^2C-bus compliance).
I2C0_SDA	L16	E6	93	133	[10]	I; F	I/O	I^2C data input/output. Open-drain output (for I^2C-bus compliance).
Reset and wake-up pins								
$\overline{\text{RESET}}$	D9	B6	128	185	[11]	I; IA	I	External reset input: A LOW on this pin resets the device, causing I/O ports and peripherals to take on their default states, and processor execution to begin at address 0. This pin does not have an internal pull-up.

7.12 Memory mapping

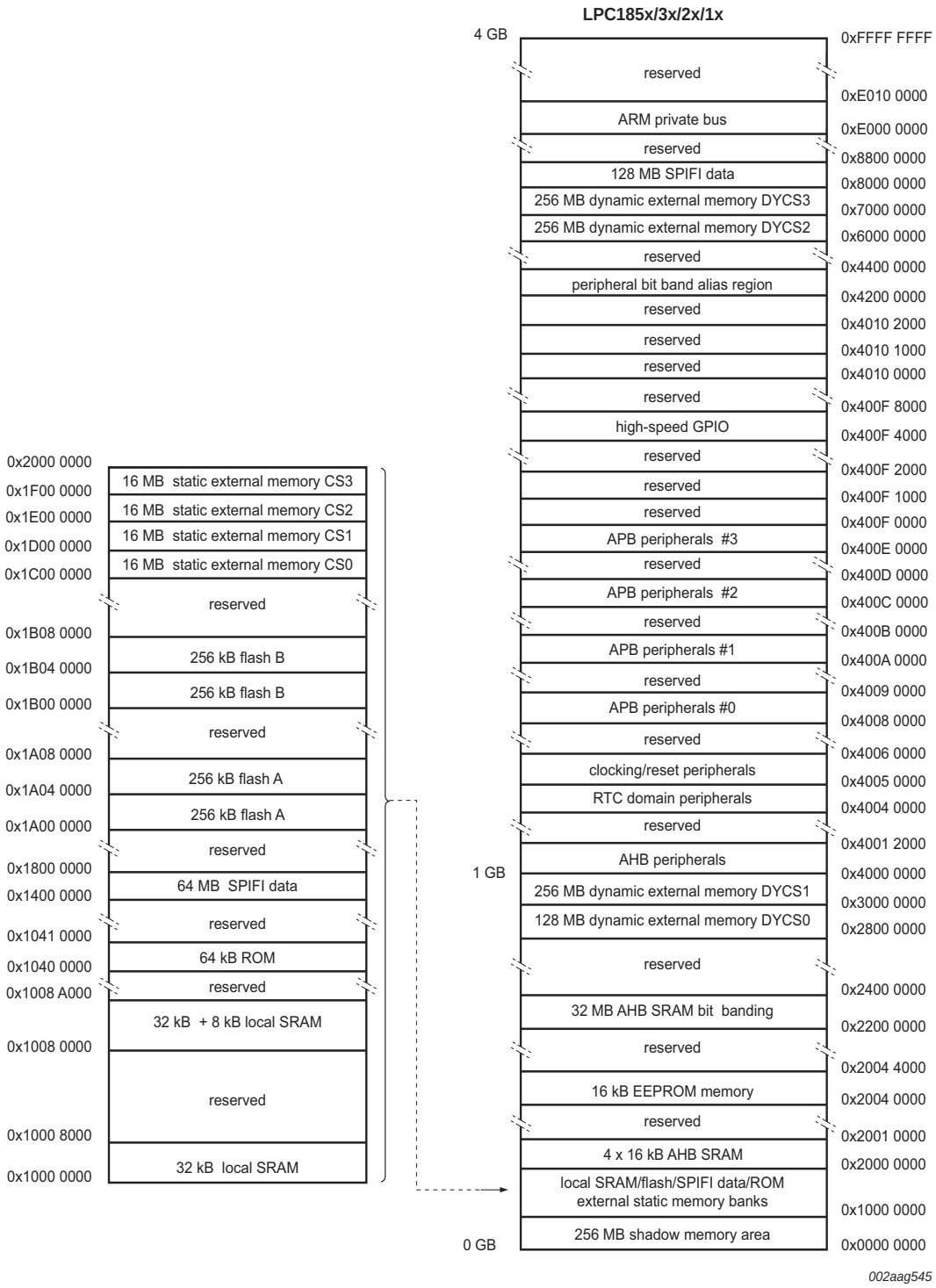


Fig 7. LPC185x/3x/2x/1x Memory mapping (overview)

- 15 gray-level monochrome, 3375 color STN, and 32 K color palettized TFT support.
- 1, 2, or 4 bits-per-pixel (bpp) palettized displays for monochrome STN.
- 1, 2, 4, or 8 bpp palettized color displays for color STN and TFT.
- 16 bpp true-color non-palettized for color STN and TFT.
- 24 bpp true-color non-palettized for color TFT.
- Programmable timing for different display panels.
- 256 entry, 16-bit palette RAM, arranged as a 128 × 32-bit RAM.
- Frame, line, and pixel clock signals.
- AC bias signal for STN, data enable signal for TFT panels.
- Supports little and big-endian, and Windows CE data formats.
- LCD panel clock can be generated from the peripheral clock, or from a clock input pin.

7.15.9 Ethernet

Remark: The ethernet controller is available on parts LPC185x and LPC183x. Ethernet is not available on parts LPC182x and LPC181x.

7.15.9.1 Features

- 10/100 Mbit/s.
- DMA support.
- Power management remote wake-up frame and magic packet detection.
- Supports both full-duplex and half-duplex operation
  - Supports CSMA/CD Protocol for half-duplex operation.
  - Supports IEEE 802.3x flow control for full-duplex operation.
  - Optional forwarding of received pause control frames to the user application in full-duplex operation.
  - Back-pressure support for half-duplex operation.
  - Automatic transmission of zero-quanta pause frame on deassertion of flow control input in full-duplex operation.
- Support for IEEE 1588 time stamping and IEEE 1588 advanced time stamping (IEEE 1588-2008 v2).

7.16 Digital serial peripherals

7.16.1 UART

Remark: The LPC185x/3x/2x/1x contain one UART with standard transmit and receive data lines.

UART1 also provides a full modem control handshake interface and support for RS-485/9-bit mode allowing both software address detection and automatic address detection using 9-bit mode.

UART1 includes a fractional baud rate generator. Standard baud rates such as 115200 Bd can be achieved with any crystal frequency above 2 MHz.

transfers, with frames of 4 bit to 16 bit of data flowing from the master to the slave and from the slave to the master. In practice, often only one of these data flows carries meaningful data.

7.16.3.1 Features

- Maximum SSP speed in full-duplex mode of 25 Mbit/s; for transmit only 50 Mbit/s (master) and 15 Mbit/s (slave).
- Compatible with Motorola SPI, 4-wire Texas Instruments SSI, and National Semiconductor Microwire buses.
- Synchronous serial communication.
- Master or slave operation.
- Eight-frame FIFOs for both transmit and receive.
- 4-bit to 16-bit frame.
- Connected to the GPDMA.

7.16.4 I^2C-bus interface

Remark: The LPC185x/3x/2x/1x contain two I^2C-bus interfaces.

The I^2C-bus is bidirectional for inter-IC control using only two wires: a Serial Clock line (SCL) and a Serial Data line (SDA). Each device is recognized by a unique address and can operate as either a receiver-only device (for example, an LCD driver) or a transmitter with the capability to both receive and send information (such as memory). Transmitters and/or receivers can operate in either master or slave mode, depending on whether the chip has to initiate a data transfer or is only addressed. The I^2C-bus interface is a multi-master bus and can be controlled by more than one bus master connected to it.

7.16.4.1 Features

- I^2C0 is a standard I^2C-bus compliant bus interface with open-drain pins. I^2C0 also supports Fast mode plus with bit rates up to 1 Mbit/s.
- I^2C1 uses standard I/O pins with bit rates of up to 400 kbit/s (Fast I^2C-bus).
- Easy to configure as master, slave, or master/slave.
- Programmable clocks allow versatile rate control.
- Bidirectional data transfer between masters and slaves.
- Multi-master bus (no central master).
- Arbitration between simultaneously transmitting masters without corruption of serial data on the bus.
- Serial clock synchronization allows devices with different bit rates to communicate via one serial bus.
- Serial clock synchronization can be used as a handshake mechanism to suspend and resume serial transfer.
- The I^2C-bus can be used for test and diagnostic purposes.
- All I^2C-bus controllers support multiple address recognition and a bus monitor mode.

7.16.5 I^2S interface

Remark: The LPC185x/3x/2x/1x contain two I^2S interfaces.

- Selectable time period from ($T_{cy(WDCLK)} \times 256 \times 4$) to ($T_{cy(WDCLK)} \times 2^{24} \times 4$) in multiples of $T_{cy(WDCLK)} \times 4$.
- The Watchdog Clock (WDCLK) uses the IRC as the clock source.

7.18 Analog peripherals

7.18.1 Analog-to-Digital Converter

Remark: The LPC185x/3x/2x/1x contain two 10-bit ADCs. All input channels are shared between ADC0 and ADC1.

7.18.1.1 Features

- 10-bit successive approximation analog to digital converter.
- Input multiplexing among 8 pins.
- Power-down mode.
- Measurement range 0 to VDDA.
- Sampling frequency up to 400 kSamples/s.
- Burst conversion mode for single or multiple inputs.
- Optional conversion on transition on ADCTRIG0 or ADCTRIG1 pins, combined timer outputs 8 or 15, or the PWM output MCOA2.
- Individual result registers for each A/D channel to reduce interrupt overhead.
- DMA support.

7.18.2 Digital-to-Analog Converter (DAC)

7.18.2.1 Features

- 10-bit resolution.
- Monotonic by design (resistor string architecture).
- Controllable conversion speed.
- Low power consumption.

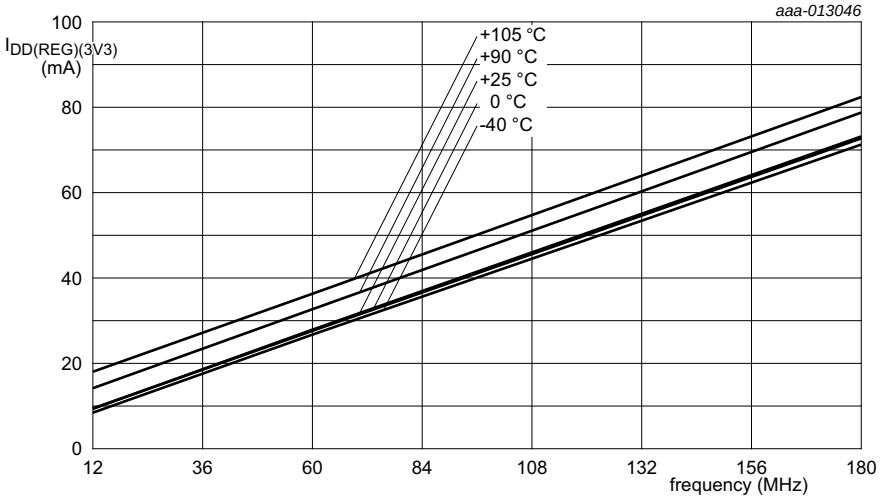
7.19 Peripherals in the RTC power domain

7.19.1 RTC

The Real-Time Clock (RTC) is a set of counters for measuring time when system power is on, and optionally when it is off. It uses little power when the CPU does not access its registers, especially in the reduced power modes. A separate 32 kHz oscillator clocks the RTC. The oscillator produces a 1 Hz internal time reference and is powered by its own power supply pin, VBAT.

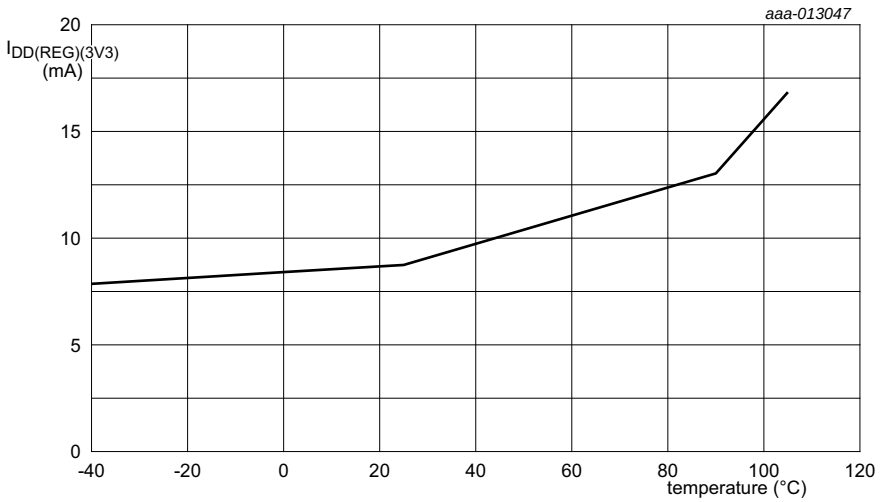
7.19.1.1 Features

- Measures the passage of time to maintain a calendar and clock. Provides seconds, minutes, hours, day of month, month, year, day of week, and day of year.
- Ultra-low power design to support battery powered systems. Uses power from the CPU power supply when it is present.



Conditions: active mode entered executing code while (1){} from SRAM; $V_{DD(REG)(3V3)}$ = 3.3 V; system PLL enabled; IRC enabled; all peripherals disabled; all peripheral clocks disabled.

Fig 12. Typical supply current versus core frequency in active mode; code executed from SRAM



Conditions: $V_{DD(REG)(3V3)}$ = 3.3 V; internal pull-up resistors disabled; system PLL disabled; IRC enabled; all peripherals disabled; all peripheral clocks disabled. CCLK = 12 MHz.

Fig 13. Typical supply current versus temperature in sleep mode

10.4 BOD and band gap static characteristics

Table 13. BOD static characteristics[1]

T_{amb} = 25 °C; simulated values for nominal processing.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
V_{th}	threshold voltage	interrupt level 2					
		assertion		-	2.95	-	V
		de-assertion		-	3.03	-	V
		interrupt level 3					
		assertion		-	3.05	-	V
		de-assertion		-	3.13	-	V
		reset level 2					
		assertion		-	2.1	-	V
		de-assertion		-	2.18	-	V
		reset level 3					
		assertion		-	2.2	-	V
		de-assertion		-	2.28	-	V

[1] Interrupt and reset levels are selected by writing to the BODLV1/2 bits in the control register CREGE0, see the *LPC18xx user manual*.

Table 14. Band gap characteristics

$V_{DDA(3V3)}$ over specified ranges; T_{amb} = −40 °C to +105 °C; unless otherwise specified

Symbol	Parameter		Min	Typ	Max	Unit
$V_{ref(bg)}$	band gap reference voltage	[1]	0.707	0.745	0.783	mV

[1] Based on characterization, not tested in production.

11.18 SPIFI

Table 36. Dynamic characteristics: SPIFI

T_{amb} = −40 °C to +105 °C; 2.4 V ≤ $V_{DD(REG)(3V3)}$ ≤ 3.6 V; 2.7 V ≤ $V_{DD(IO)}$ ≤ 3.6 V. C_L =20 pF. Sampled at 90 % and 10 % of the signal level. EHS = 1 for all pins. Simulated values.

Symbol	Parameter	Min	Max	Unit
$T_{cy(clk)}$	clock cycle time	9.6	-	ns
t_{DS}	data set-up time	3.2	-	ns
t_{DH}	data hold time	0	-	ns
$t_{v(Q)}$	data output valid time	-	3.2	ns
$t_{h(Q)}$	data output hold time	0.6	-	ns

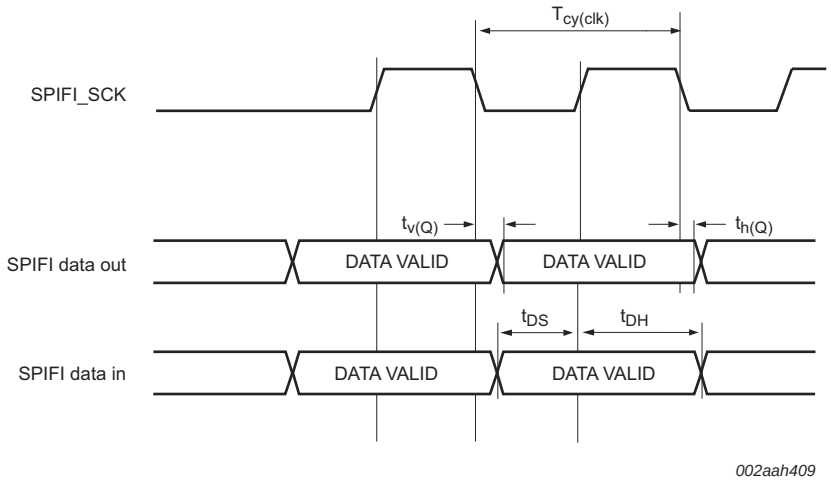
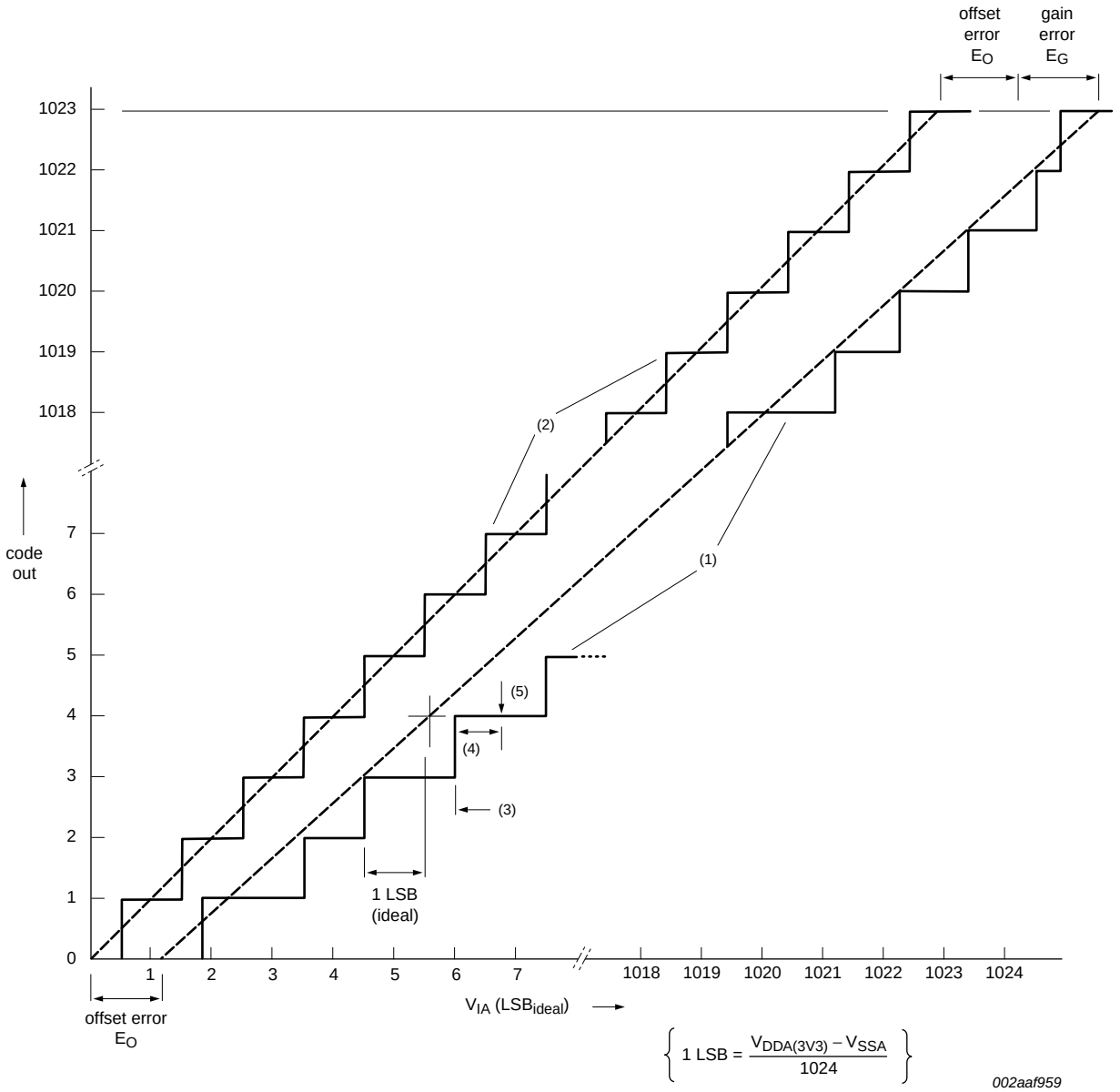


Fig 38. SPIFI timing (Mode 0)



(1) Example of an actual transfer curve.

(2) The ideal transfer curve.

(3) Differential linearity error (E_D).

(4) Integral non-linearity ($E_{L(adj)}$).

(5) Center of a step of the actual transfer curve.

Fig 39. 10-bit ADC characteristics

13.3 RTC oscillator

In the RTC oscillator circuit, only the crystal (XTAL) and the capacitances C_{RTCX1} and C_{RTCX2} need to be connected externally. Typical capacitance values for C_{RTCX1} and C_{RTCX2} are $C_{RTCX1/2}$ = 20 (typical) $\pm$ 4 pF.

An external clock can be connected to RTCX1 if RTCX2 is left open. The recommended amplitude of the clock signal is $V_{i(RMS)}$ = 100 mV to 200 mV with a coupling capacitance of 5 pF to 10 pF.

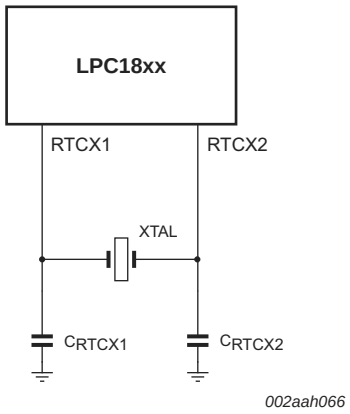


Fig 43. RTC 32 kHz oscillator circuit

13.4 XTAL and RTCX Printed Circuit Board (PCB) layout guidelines

Connect the crystal on the PCB as close as possible to the oscillator input and output pins of the chip. Take care that the load capacitors C_{X1}, C_{X2}, and C_{X3} in case of third overtone crystal usage have a common ground plane. Also connect the external components to the ground plain. To keep the noise coupled in via the PCB as small as possible, make loops and parasitics as small as possible. Choose smaller values of C_{X1} and C_{X2} if parasitics increase in the PCB layout.

Ensure no high-speed or high-drive signals are near the RTCX1/2 signals.

13.5 Standard I/O pin configuration

Figure 44 shows the possible pin modes for standard I/O pins with analog input function:

- Digital output driver enabled/disabled
- Digital input: Pull-up enabled/disabled
- Digital input: Pull-down enabled/disabled
- Digital input: Repeater mode enabled/disabled
- Digital input: Input buffer enabled/disabled
- Analog input

The default configuration for standard I/O pins is input buffer disabled and pull-up enabled. The weak MOS devices provide a drive capability equivalent to pull-up and pull-down resistors.

19. Legal information

19.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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